TOSHIBA CMOS Digital Integrated Circuit Silicon Monolithic

TC74HC652AP

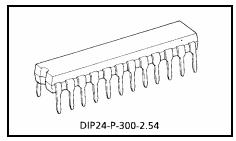
Octal Bus Transceiver/Register (3-state)

The TC74HC652A is high speed CMOS OCTAL BUS TRANSCEIVER/REGISTER fabricated with silicon gate CMOS technology.

It achieves the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation.

This device is bus transceiver with 3-state outputs, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the internal registers.

When the enable input GAB and $\ GBA$ are held high, the A1 thru A8 become inputs and the B1 thru B8 become outputs. When the GAB and $\ \overline{GBA}$ are held low, the A1 thru A8 become output and the B1 thru B8 become inputs. When GAB is low and $\ \overline{GBA}$ is high, the outputs functions of the A and B Busses are disabled.



Weight : 1.50 g (typ.)

The select inputs (SAB, SBA) can multiplex sort and real-time (transparent mode) data.

Data on the A Bus or B Bus can be clocked into the registers on the positive going transition of either CAB or CBA clock inputs, respectively.

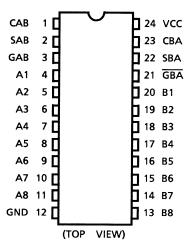
All inputs are equipped with protection circuits against static discharge or transient excess voltage.

Features (Note 1) (Note 2)

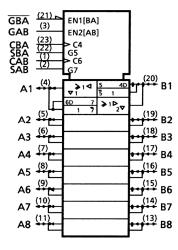
- High speed: $f_{max} = 73 \text{ MHz}$ (typ.) at $V_{CC} = 5 \text{ V}$
- Low power dissipation: $ICC = 4 \mu A \text{ (max)}$ at $Ta = 25^{\circ}C$
- High noise immunity: VNIH = VNIL = 28% VCC (min)
- · Output drive capability: 15 LSTTL loads
- Symmetrical output impedance: | I_{OH} | = I_{OL} = 6 mA (min)
- Balanced propagation delays: $t_{pLH} \simeq t_{pHL}$
- Wide operating voltage range: VCC (opr) = 2 to 6 V
- Pin and function compatible with 74LS652
 - Note 1: Do not apply a signal to any bus terminal when it is in the output mode. Damage may result.
 - Note 2: All floating (high impedance) bus terminals must have their input levels fixed by means of pull up or pull down resistors.

2007-10-01

Pin Assignment



IEC Logic Symbol



Truth Table

GAB	GBA	CAB	СВА	SAB	SBA	Α	В	Function				
		X (Note)	X (Note)	Х	Х	Inputs Z	Inputs Z	The output functions of A and B busses are disabled.				
L	Н			Х	х	Х	Х	Both A and B busses are used as inputs to the internal flip-flops. Data on the Bus will be stored on the rising edge of the clock.				
		Х	Х			Outputs	Inputs					
			(Note)	Х	L	L	L	The data on the B bus are displayed on the A bus.				
		(Note)	(Note)			Н	Н					
		Х	•			L	L	The data on the B bus are displayed on the A bus,				
L	L	(Note)		Х	L	Н	Н	and are stored into the B storage flip-flops on the rising edge of CBA.				
		X (Note)	X (Note)	Х	Н	Qn	Х	The data in the B storage flip-flops are displayed on the A bus.				
		Х	_	Х	Н	L	L	The data on the B bus are stored into the B				
		(Note)				Н	Н	storage flip-flops on the rising edge of CBA, and the stored data propagate directly onto the A bus.				
		x x		L	Х	Inputs	Outputs					
			X (N=+=)			L	L	The data on the A bus are displayed on the B bus.				
		(Note) (N	(Note)			Н	Н					
			Х		.,	L	L	The data on the A bus are displayed on the B bus,				
Н	Н		(Note)	L	Х	Н	Н	and are stored into the A storage flip-flops on the rising edge of CAB.				
		X (Note)	X (Note)	Н	Х	Х	Qn	The data in the A storage flip-flops are displayed on the B bus.				
			X (Note)			L	L	The data on the A bus are stored into the A				
				Н	X	Н	Н	storage flip-flops on the rising edge of CAB, and the stored data propagate directly onto the B bus.				
		X	Х			Outputs	Outputs	The data in the A storage flip-flops are displayed				
Н	L	(Note)	(Note)	Н	Н	Qn	Qn	on the B bus, and the data in the B storage flip-flops are displayed onthe A.				

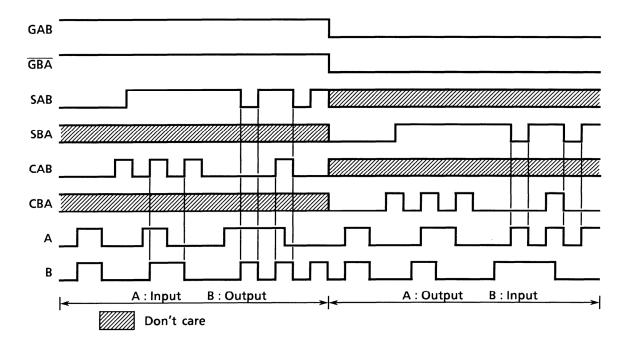
X: Don't care

Qn: The data stored into the internal flip-flops by most recent low to high transition of the clock inputs.

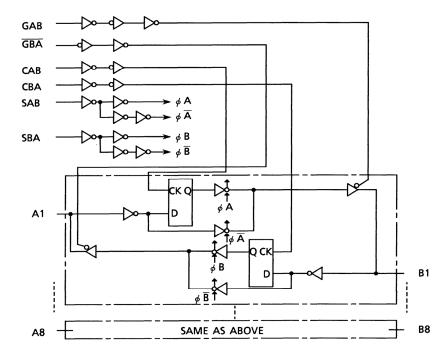
Z: High impedance

Note: The clocks are not internally gated with either output enable or select inputs. Therefore, data on the A and/or B busses may be clocked into the storage flip-flops at any time.

Timing Chart



System Diagram



Absolute Maximum Ratings (Note 1)

Characteristics	Symbol	Rating	Unit
Supply voltage range	V _{CC}	–0.5 to 7	V
DC input voltage	V _{IN}	-0.5 to V_{CC} + 0.5	V
DC output voltage	V _{OUT}	-0.5 to V _{CC} + 0.5	V
Input diode current	I _{IK}	±20	mA
Output diode current	lok	±20	mA
DC output current	lout	±35	mA
DC V _{CC} /ground current	Icc	±75	mA
Power dissipation	PD	500 (Note 2)	mW
Storage temperature	T _{stg}	-65 to 150	°C

Note 1: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 2: 500 mW in the range of Ta = -40 to 65°C. From Ta = 65 to 85°C a derating factor of -10 mW/°C shall be applied until 300 mW.

Operating Ranges (Note)

Characteristics	Symbol	Rating	Unit
Supply voltage	V _{CC}	2 to 6	V
Input voltage	V _{IN}	0 to V _{CC}	V
Output voltage	V _{OUT}	0 to V _{CC}	V
Operating temperature	T _{opr}	−40 to 85	°C
		0 to 1000 (V _{CC} = 2.0 V)	
Input rise and fall time	t _r , t _f	0 to 500 (V _{CC} = 4.5 V)	ns
		0 to 400 ($V_{CC} = 6.0 \text{ V}$)	

Note: The operating ranges must be maintained to ensure the normal operation of the device.
Unused inputs must be tied to either VCC or GND.

Electrical Characteristics

DC Characteristics

Characteristics	Symbol	Test Condition			-	Га = 25°C		Ta = - 85	- Unit	
Characteristics	Symbol				Min	Тур.	Max	Min		Max
				2.0	1.50	_	_	1.50	_	
High-level input voltage	V _{IH}		_	4.5	3.15	_	_	3.15	_	V
				6.0	4.20	_	_	4.20	_	
				2.0	_		0.50		0.50	
Low-level input voltage	V _{IL}		_	4.5	_	_	1.35	_	1.35	V
				6.0	_	_	1.80	_	1.80	
				2.0	1.9	2.0	_	1.9	_	
	V _{OH}	V _{IN} = V _{IH} or V _{IL}	$I_{OH} = -20 \mu A$	4.5	4.4	4.5	_	4.4	_	V
High-level output voltage				6.0	5.9	6.0	—	5.9	_	
			$I_{OH} = -6 \text{ mA}$	4.5	4.18	4.31	_	4.13	_	
			$I_{OH} = -7.8 \text{ mA}$	6.0	5.68	5.80	_	5.63	_	
		V _{IN}		2.0		0.0	0.1		0.1	
			$I_{OL} = 20 \ \mu A$	4.5	_	0.0	0.1		0.1	
Low-level output voltage	V _{OL}	= V _{IH} or		6.0		0.0	0.1	_	0.1	V
		V _{IL}	I _{OL} = 6 mA	4.5	_	0.17	0.26	_	0.33	
			$I_{OL} = 7.8 \text{ mA}$	6.0		0.18	0.26	—	0.33	
3-state output off-state current	I _{OZ}	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $V_{OUT} = V_{CC} \text{ or GND}$		6.0	_		±0.5		±5.0	μА
Input leakage current	I _{IN}	V _{IN} = V _{CC} or GND		6.0	_	_	±0.1	_	±1.0	μА
Quiescent supply current			6.0		_	4.0	_	40.0	μА	

Timing Requirements (input: $t_r = t_f = 6$ ns)

Characteristics	Symbol	Test Condition		Ta =	25°C	Ta = -40 to 85°C	Unit	
			V _{CC} (V)	Тур.	Limit	Limit		
Minimum nuloo width	4		2.0	_	75	95	ns	
Minimum pulse width	t _{W (L)}	_	4.5	_	15	19		
(CK)	t _{W (H)}		6.0	_	13	16		
	t _s		2.0	_	50	65	ns	
Minimum set-up time		_	4.5	_	10	13		
			6.0	_	9	11		
			2.0	_	5	5		
Minimum hold time	th	_	4.5	_	5	5	ns	
			6.0	_	5	5		
			2.0	_	6	5	MHz	
Clock frequency	f	_	4.5	_	31	25		
			6.0		36	29		



AC Characteristics (input: $t_r = t_f = 6$ ns)

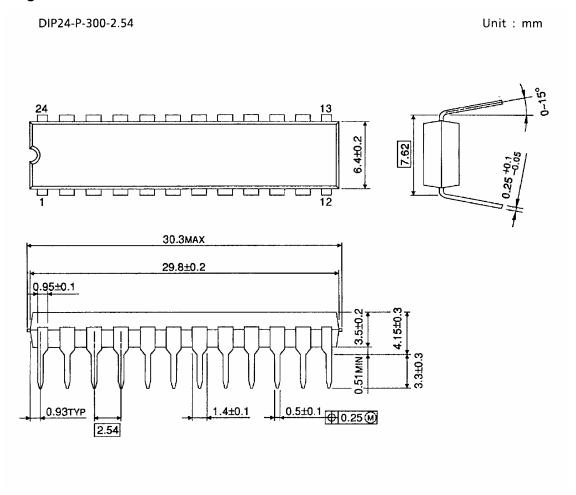
Characteristics	Symbol	Test Condition			-	Га = 25°C		Ta = -40 to 85°C		- Unit
Characteristics	Symbol		CL (pF)	V _{CC} (V)	Min	Тур.	Max	Min	Max	Offic
	+			2.0	_	25	60	_	75	
Output transition time	t _{TLH}	_	50	4.5	_	7	12	_	15	ns
	t _{THL}			6.0	_	6	10	_	13	
				2.0	_	74	150	_	190	
			50	4.5	_	21	30	_	38	
Propagation delay time	t _{pLH}			6.0	_	18	26	_	32	
(BUS-bus)	t _{pHL}	_		2.0	_	91	190	_	240	ns
(====)			150	4.5	_	26	38		48	
				6.0	_	22	32		41	
				2.0	_	98	210	_	265	
			50	4.5	_	28	42	_	53	
Propagation delay time	t _{pLH}			6.0	_	24	36	_	45	
(CAB, CBA-bus)	t _{pHL}	_	150	2.0	_	116	250	_	315	- ns
(Orib, Obribae)	r			4.5	_	33	50	_	63	
				6.0	_	28	43	_	54	
	t _P LH t _P HL	_		2.0	_	81	170	_	215	- ns
			50	4.5	_	23	34		43	
Propagation delay time				6.0	_	20	29		37	
(SAB, SBA-bus)			150	2.0	_	98	210	_	265	
(SAB, SBA-Dus)				4.5	_	28	42	_	53	
				6.0	_	24	36	_	45	
				2.0	_	74	175	_	220	
			50	4.5	_	21	35	_	44	
Propagation enable	t _{pZL}			6.0	_	18	30	_	37	
time (GAB, GBA -bus)	t _{pZH}	$R_L = 1 \text{ k}\Omega$		2.0	_	91	215	_	270	ns
(GAB, GBA -bus)	P =- · ·		150	4.5	_	26	43	_	54	
				6.0	_	22	37	_	46	
				2.0	_	50	175	_	220	
Output disable time	t_{pLZ}	$R_L = 1 \text{ k}\Omega$	50	4.5	_	21	35		44	ns
(GAB, GBA -bus)	t_{pHZ}	_		6.0		18	30		37	
				2.0	6	19	_	5	_	
Maximum clock	f _{max}	_	50	4.5	31	67	_	25	_	MHz
frequency	max			6.0	36	79	_	29	_	1411 12
Input capacitance	C _{IN}	_	<u> </u>		_	5	10	_	10	pF
Output capacitance	C _{OUT}	_			_	13	_	_	_	pF
Power dissipation capacitance	C _{PD} (Note)	_			_	39	_	_	_	pF

Note: CPD is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation:

 I_{CC} (opr) = $C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/8$ (per bit)

Package Dimensions



Weight: 1.50 g (typ.)

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20070701-EN GENERAL

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